

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **07-157668**
(43)Date of publication of application : **20.06.1995**

(51)Int.CI.

C08L101/02
C08F290/02
C08K 5/06
C09D 4/00
C09D 5/00
C09D 11/02
D21H 19/24

(21)Application number : **05-339160**

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(22)Date of filing : **06.12.1993**

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(54) RADIATION-CURING RESIN COMPOSITION AND CURED PRODUCT THEREFROM

(57)Abstract:

PURPOSE: To obtain the subject composition which has a high curing rate and can give a cured product excellent in gloss and adhesion to substrate and resistant to cracking even when bent by mixing a specified polymer with a vinyl ether compound and a photo-cationic polymerization initiator.

CONSTITUTION: This resin composition comprises desirably 0.5-40wt.% polymer of an unsaturated compound [e.g. a polymer of (meth)acrylate], desirably 10-99wt.% vinyl ether compound (e.g. tetraethylene glycol divinyl ether) and desirably 0.1-10wt.% photo-cationic polymerization initiator (e.g. triphenylsulfonium hexafluoroantimonate).

LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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